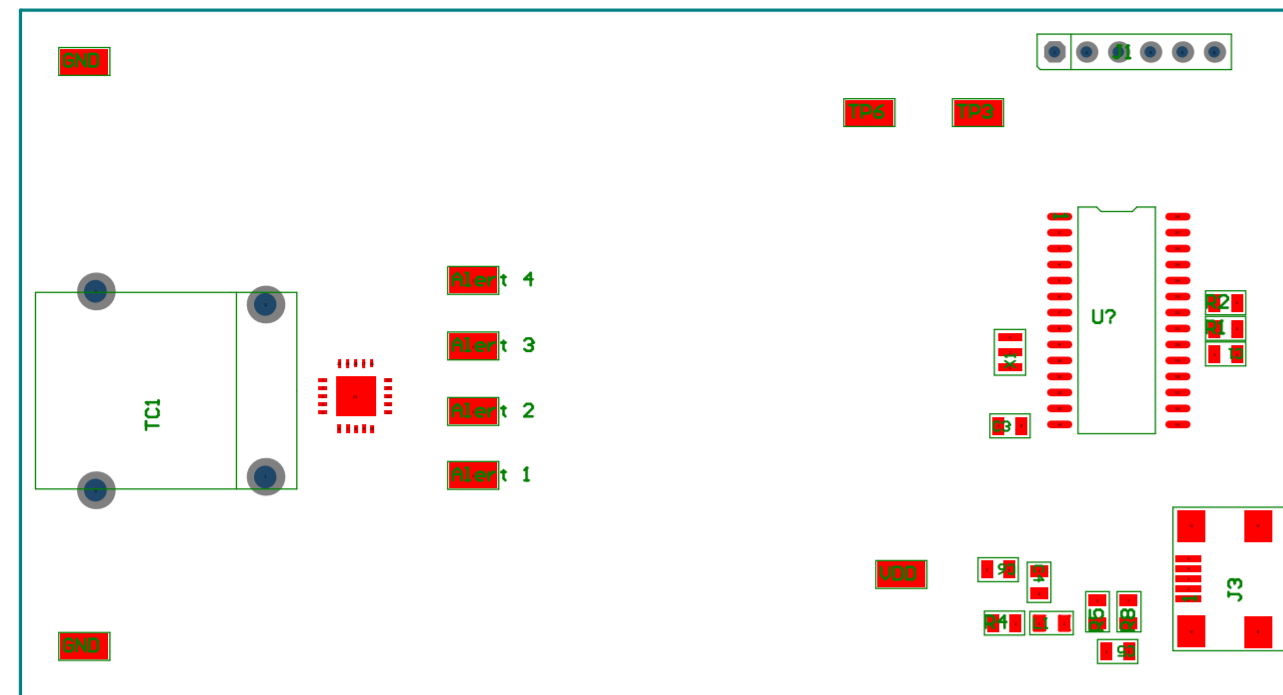

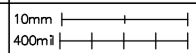


REV	ECO	Comments	Date



ASSEMBLY NOTES:

1. ALL COMPONENTS SHALL BE RoHS COMPLIANT.
2. ALL UNUSED THROUGH HOLE COMPONENT LOCATIONS SHALL BE FREE OF SOLDER.
3. ALL COMPONENTS SHALL BE MOUNTED FLUSH TO THE BOARD, EXCEPT AS NOTED.
4. FINISHED BOARD SHALL BE FREE OF ALL RESIDUES.
5. ALL LEADS SHALL BE TRIMMED TO A MAXIMUM HEIGHT OF 2mm
6. PLACE LABEL (.ProjectBoardName) AT THE LOCATION INDICATED.
- 7.

 MICROCHIP Microchip Technology Inc. 2355 W. Chandler Blvd. Chandler, AZ 85224	TITLE: MCP9600 Evaluation Board		PART NUMBER: 02-10413	
	PCB DESIGNER: E. Haile		GERBER FILE: Top Assembly Drawing	
	ENGINEER: E. Haile	BOARD NUMBER: 04-10413	DOCUMENT NUMBER: 02-10413 -D	DATE: 4/24/2015
	PCB FILE NAME: 04-10413-R1.PcbDoc	LAYER NAME: Assy TOP (M11)	REV: 1	

1

2

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4

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6

A

A

B

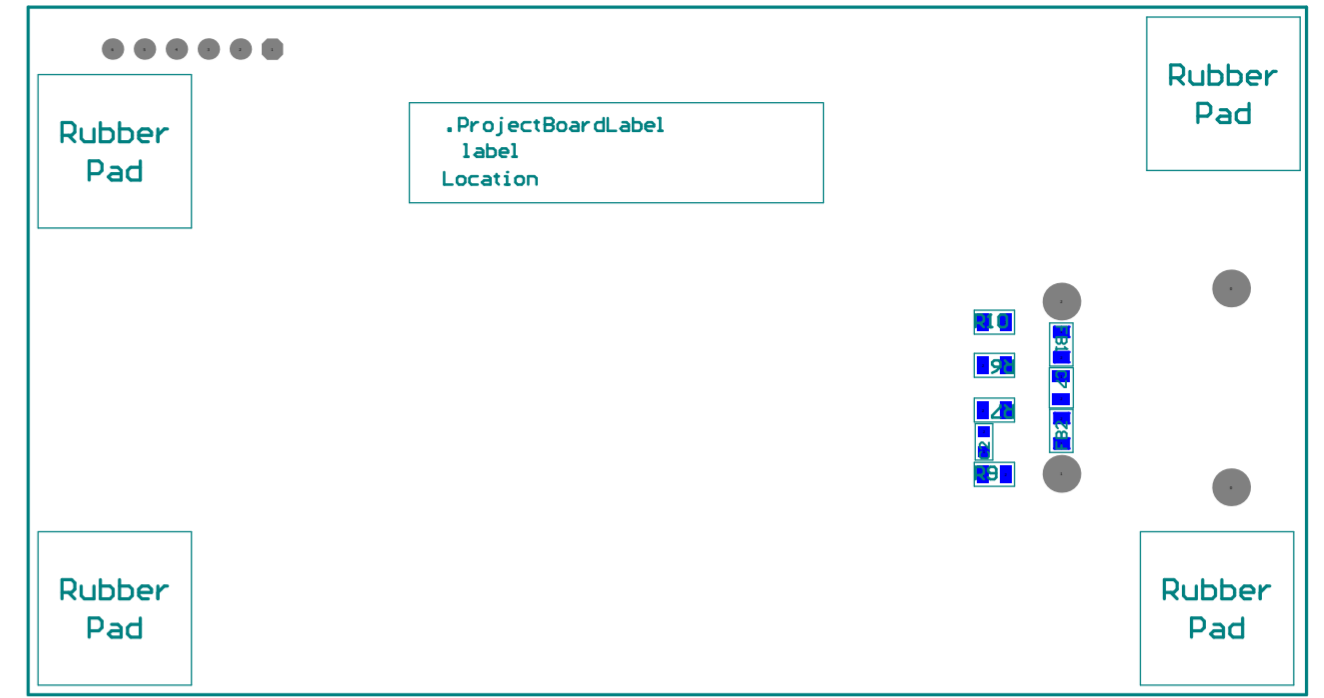
B



C

C

D

D



 MICROCHIP Microchip Technology Inc. 2355 W. Chandler Blvd. Chandler, AZ 85224	TITLE: MCP9600 Evaluation Board			PART NUMBER: 02-10413
	ASSEMBLY VARIANT: (No Variations)			
	PCB DESIGNER: E. Haile	GERBER FILE: Bottom Assembly Drawing		
	ENGINEER: E. Haile	BOARD NUMBER: 04-10413	DOCUMENT NUMBER: 02-10413 -D	DATE: 4/24/2015
PCB FILE NAME: 04-10413-R1.PcbDoc	LAYER NAME: Assy BOT (M10)	REV: 1		

1

2

3

4

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6



GND

MCP9600 Thermocouple IC

Eval Bd.

ADM00665



J1

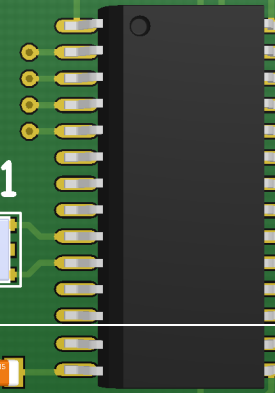


SCL



SDA

U3



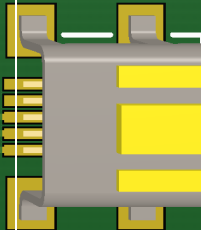
R2
R1
C1



X1

C3

J3



C6
R4
L1
C4
R5
R8
C5

VDD



Alert 4



Alert 3



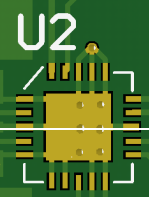
Alert 2



Alert 1

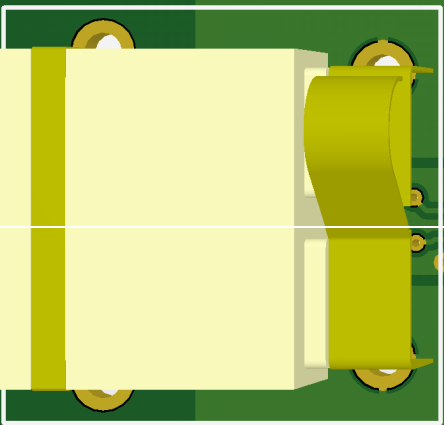


MICROCHIP



U2

TC1



GND



